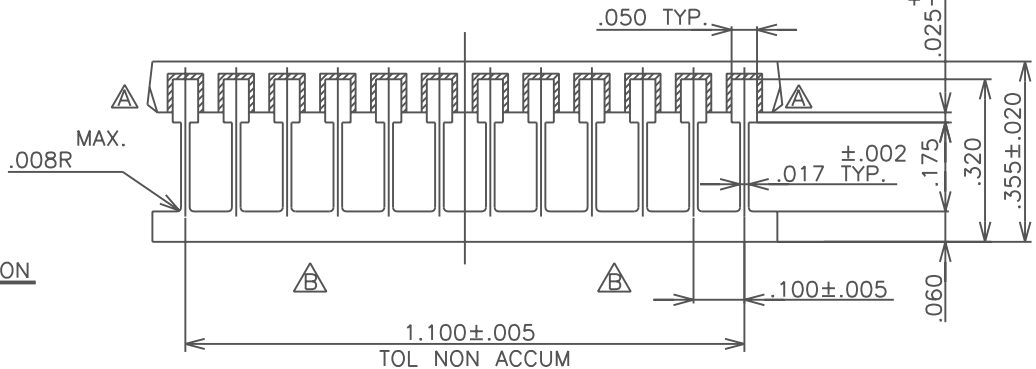
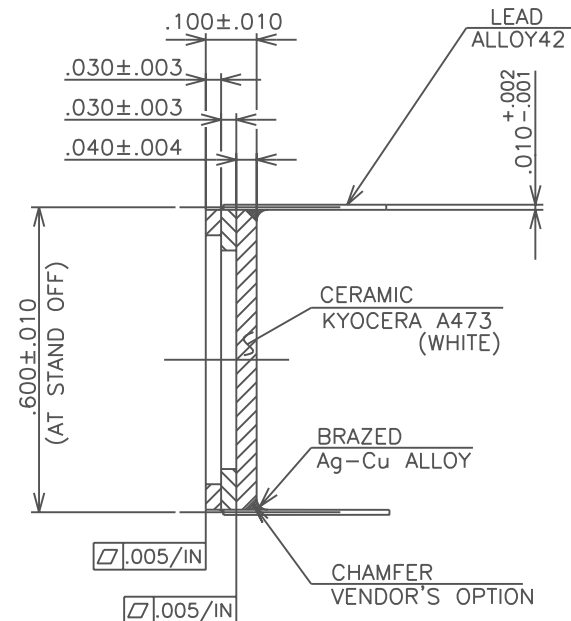
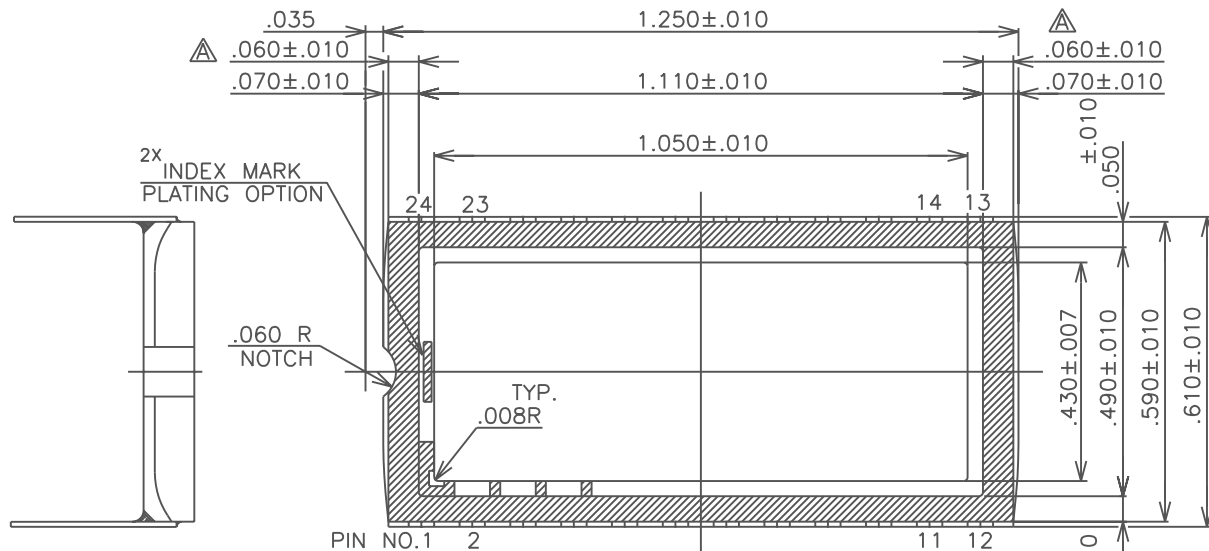


SSM P/N HYB02413



NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. LEAD RESISTANCE : 0.2 OHM MAX.
3. SEAL AREA TO BE METALLIZED.
4. SEAL RING TO BE FLOATING FROM ANY PINS.
5. DIE ATTACH AREA TO BE NOT METALLIZED.

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
	△	CORRECTED : LEAD FRAME TIE BAR	JAN.25.'01	T.S/H.K	H.TA/S.NI	H.SA	UNLESS OTHERWISE SPECIFIED	S.F	M.H	K.O	MAR.19.'86
		CHANGED:END CHAMFER CONFIGURATION.					1.0%				
	△	ADDED:.060±.010(SEAL RING WIDTH)	MAY.5.'86	T.O	K.M		N.L.T.±.005				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	SCALE	MATERIAL	DRAWING NO.			
						4 / 1	AS INDICATED	KD-H86255-B			
								SHEET			
								1 / 2			

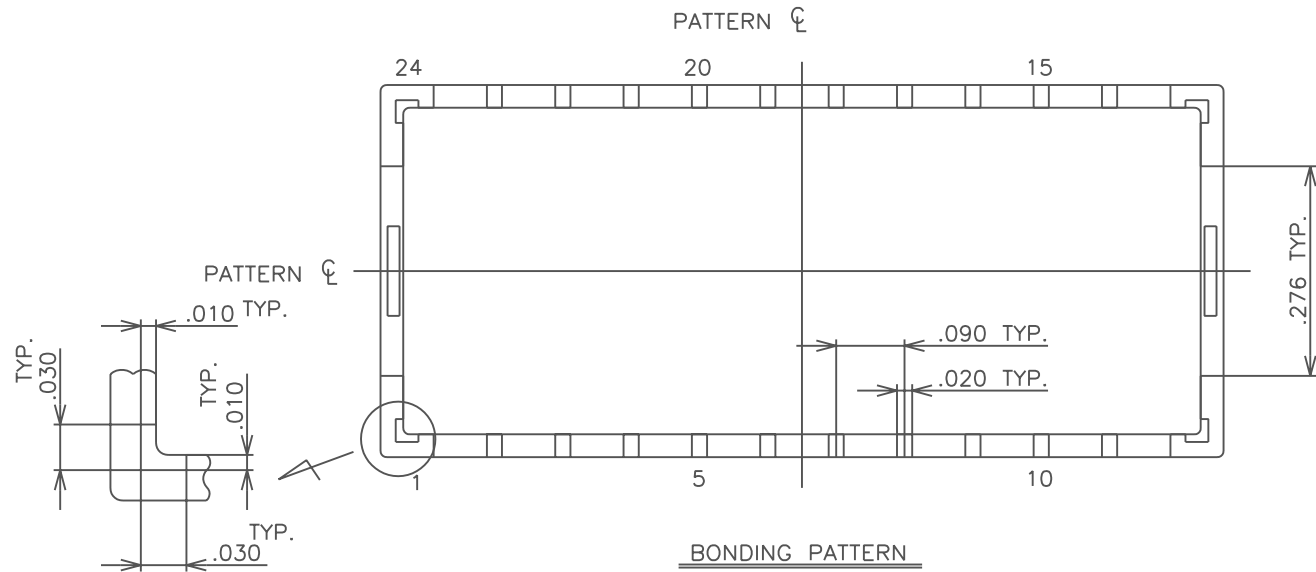
HW024S255-1 S=0 D=N



KYOCERA CORPORATION
KYOTO JAPAN



SSM P/N HYB02413



MODIFICATION						NAME	24 LEAD HYBRID PACKAGE	TOLERANCE	UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE	6 / 1	MATERIAL		S.F	M.H	K.O	MAR.19.'86
								THIRD ANGLE PROJECTION					
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-H86255-B	SHEET		2 / 2	

